502667389 02/05/2014

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT2713996

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YOSHIHITO HAGIWARA	11/19/2013
NAOKI SEKINE	11/15/2013
KOICHI TAKAHASHI	11/19/2013
YASUO NAGASHIMA	11/19/2013
MOTOKI NAKAZAWA	11/19/2013

RECEIVING PARTY DATA

Name:	SHINKAWA LTD.
Street Address:	51-1, INADAIRA 2-CHOME, MUSASHIMURAYAMA-SHI
City:	токуо
State/Country:	JAPAN
Postal Code:	208-8585

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14081104

CORRESPONDENCE DATA

 Fax Number:
 (212)940-8986

 Phone:
 212-940-8800

Email: nycuspto@kattenlaw.com

Correspondence will be sent via US Mail when the email attempt is unsuccessful.

Correspondent Name: KATTEN MUCHIN ROSENMAN LLP

Address Line 1: 575 MADISON AVENUE Address Line 2: 15TH FLOOR, IP DEPT.

Address Line 4: NEW YORK, NEW YORK 10022-2585

ATTORNEY DOCKET NUMBER: SHIN 25.502(339243-00032)	
NAME OF SUBMITTER:	SAMSON HELFGOTT
	PATENT

502667389 REEL: 032144 FRAME: 0676

Signature: /Samson Helfgott/	
Date:	02/05/2014
Total Attachments: 5 source=SHIN25502ASSIGNMENT#page1.tif source=SHIN25502ASSIGNMENT#page2.tif source=SHIN25502ASSIGNMENT#page3.tif source=SHIN25502ASSIGNMENT#page4.tif source=SHIN25502ASSIGNMENT#page5.tif	

PATENT REEL: 032144 FRAME: 0677

Title of Invention	WIRE BONDING APPARATUS AND BONDING METHOD		
As the below	As the below named inventor, I hereby declare that:		
This declarat	1 1 4 4		
is timected to	United States application or PCT international application number 14/081,104 filed on November 15, 2013		
The above-identified application was made or authorized to be made by me.			
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.			
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.			
In consideration of One Dollar (\$1.00) and other valuable consideration, the receipt and adequacy of which are hereby acknowledged, I hereby assign, convey, transfer, deliver, set over and vest to and in SHINKAWA LTD.			
a corporation of Japan having a place of business at: 51-1, Inadaira 2-chome, Musashimurayama-shi, Tokyo, 208-8585, Japan			
its successors and assigns, absolutely and forever, my entire right, title and interest in and to the invention listed above, together with the Application, any and all Patents that may issue in the United States, and any reissues, renewals, continuations, continuation-in-parts, divisionals or extensions thereof that may be issued or granted, and all right, title and interest to the inventions contained in said Patents and Applications, for the United States, and all the rights and privileges relating thereto including but not limited to the priority rights arising from said Applications, the right to recover and take all such proceedings as may be necessary for the recovery of damages or otherwise in respect of past, present and future infringement, and the right to apply for, take and maintain patents on said inventions.			
LEGAL NAME OF INVENTOR			
Inventor:	Yoshihito HAGIWARA Date: November 19, 2013		
Signature:	YOSHIHITO HAGINADA		
	ication data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must s form. Use an additional form for each additional inventor.		

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LEGAL NAME OF INVENTOR		
Inventor:	Naoki SEKINE Date: November 15, 2013	
Signature:	W. Selvine ication data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must	
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LEGAL NAME OF INVENTOR			
Inventor:	Koichi TAKAHASHI Date: November 19, 2013		
Signature:	Koichi Takahashi		
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LEGAL NAME OF INVENTOR			
Inventor:	Yasuo NAGASHIMA Date: November 19, 2013		
Signature:	Yasho NAGASHIMA		
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LEGAL NAME OF INVENTOR			
Inventor:	Motoki NAKAZAWA Date: 19, 20/3		
Signature:	Motoki nokagawa		
	is form. Use an additional form for each additional inventor.		

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RECORDED: 02/05/2014

PATENT REEL: 032144 FRAME: 0682